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D.M. Malt  
5/30/02  
Pro. Amndt A

THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s): ITABASHI et al

Serial No.: 09/678,800

Filed: October 4, 2000

For: Electroless Copper Plating Machine Thereof, And Multi-Layer Printed Wiring Board

Group: 1741

Examiner:

RECEIVED  
MAY 10 2001  
TC 1700

**PRELIMINARY AMENDMENT**

Assistant Commissioner for Patents  
Washington, D.C. 20231

May 7, 2001

Sir:

The following preliminary amendments and remarks are respectfully submitted in connection with the above-identified application.

**IN THE TITLE:**

Please amend the title to read as follows:

Electroless Copper Plating Machine, And Multi-Layer Printed Wiring Board

**IN THE SPECIFICATION:**

Please replace the original specification with the attached Substitute Specification.

**IN THE ABSTRACT OF THE DISCLOSURE:**

Please replace the original abstract with the attached abstract.